

ABSTRACT

METHODS AND SYSTEMS FOR FLUID IMMERSION COOLING

A system for immersion cooling electronic components includes a cylindrical container having a circular cross section, a cooling element disposed in the cylindrical container and containing a first cooling fluid, and a volume of a second cooling fluid disposed in the cylindrical container and in contact with the cooling element for exchange of heat between the second cooling fluid and the first cooling fluid, the second cooling fluid comprising an immersion cooling fluid. A heat generating electronic component is disposed within the cylindrical container and at least partially immersed in the second cooling fluid for exchange of heat between the electronic component and the second cooling fluid, and a fluid circulating device is disposed in the second cooling fluid to direct a flow of the second cooling fluid through the electronic component and over the cooling element.

Fig. 1